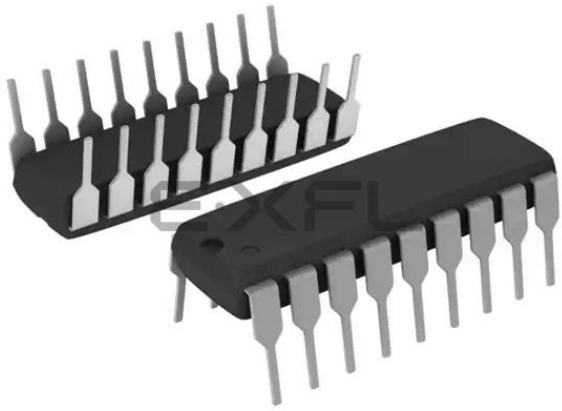

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	16
Program Memory Size	8KB (4K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 7x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f1320-h-p

5.0 MEMORY ORGANIZATION

There are three memory types in Enhanced MCU devices. These memory types are:

- Program Memory
- Data RAM
- Data EEPROM

Data and program memory use separate busses, which allows for concurrent access of these types.

Additional detailed information for Flash program memory and data EEPROM is provided in **Section 6.0 "Flash Program Memory"** and **Section 7.0 "Data EEPROM Memory"**, respectively.

5.1 Program Memory Organization

A 21-bit program counter is capable of addressing the 2-Mbyte program memory space. Accessing a location between the physically implemented memory and the 2-Mbyte address will cause a read of all '0's (a NOP instruction).

The PIC18F1220 has 4 Kbytes of Flash memory and can store up to 2,048 single-word instructions.

The PIC18F1320 has 8 Kbytes of Flash memory and can store up to 4,096 single-word instructions.

The Reset vector address is at 0000h and the interrupt vector addresses are at 0008h and 0018h.

The program memory maps for the PIC18F1220 and PIC18F1320 devices are shown in Figure 5-1 and Figure 5-2, respectively.

FIGURE 5-1: PROGRAM MEMORY MAP AND STACK FOR PIC18F1220

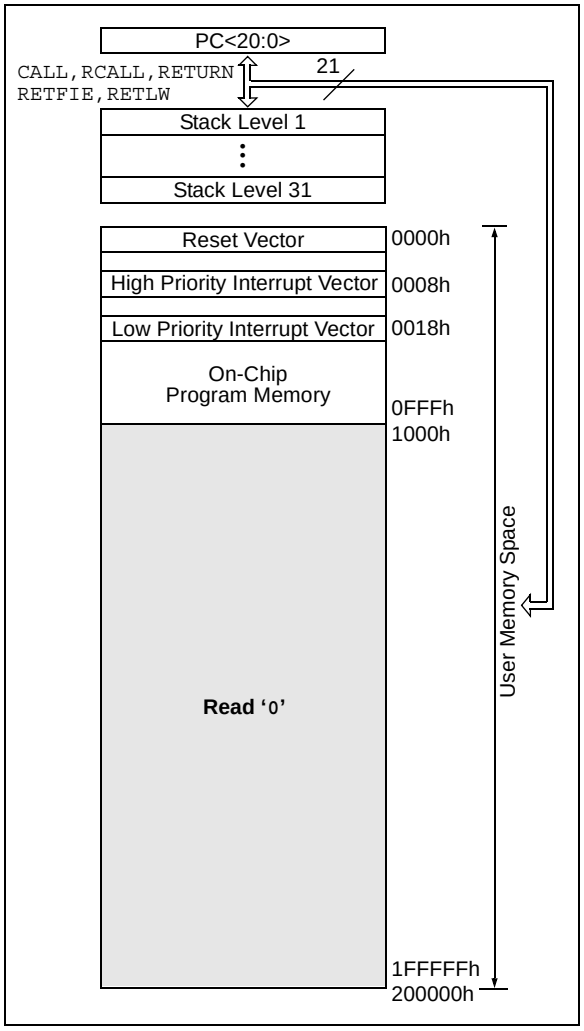
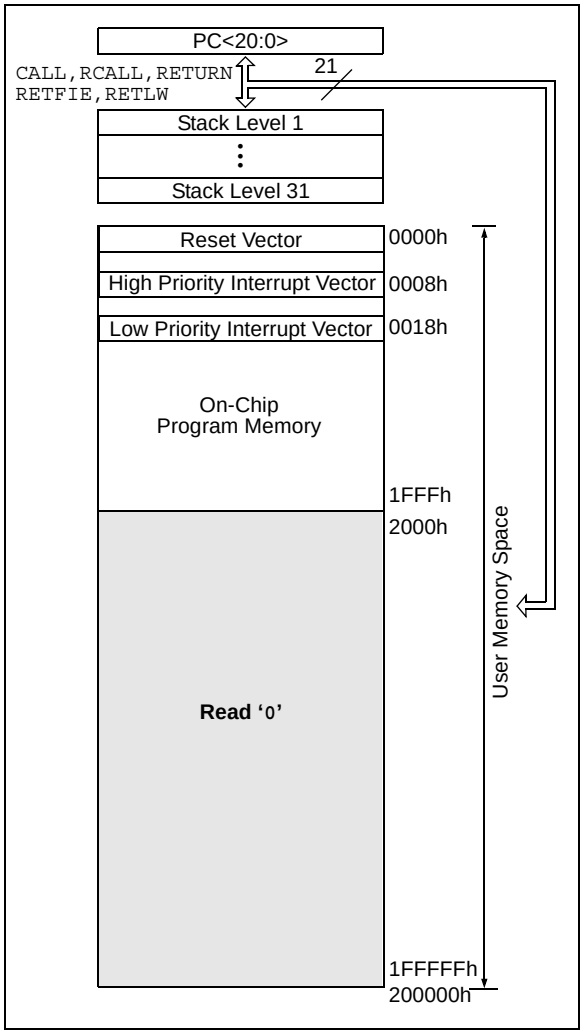


FIGURE 5-2: PROGRAM MEMORY MAP AND STACK FOR PIC18F1320



REGISTER 5-1: STKPTR: STACK POINTER REGISTER

R/C-0/0	R/C-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
STKFUL(1)	STKUNF(1)	—	SP<4:0>				
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	C = Clearable only bit

bit 7 **STKFUL:** Stack Full Flag bit(1)
1 = Stack became full or overflowed
0 = Stack has not become full or overflowed

bit 6 **STKUNF:** Stack Underflow Flag bit(1)
1 = Stack Underflow occurred
0 = Stack Underflow did not occur

bit 5 **Unimplemented:** Read as ‘0’

bit 4-0 **SP<4:0>:** Stack Pointer Location bits

Note 1: Bit 7 and bit 6 are cleared by user software or by a POR.

5.2.3 PUSH AND POP INSTRUCTIONS

Since the Top-of-Stack (TOS) is readable and writable, the ability to push values onto the stack and pull values off the stack, without disturbing normal program execution, is a desirable option. To push the current PC value onto the stack, a PUSH instruction can be executed. This will increment the Stack Pointer and load the current PC value onto the stack. TOSU, TOSH and TOSL can then be modified to place data or a return address on the stack.

The ability to pull the TOS value off of the stack and replace it with the value that was previously pushed onto the stack, without disturbing normal execution, is achieved by using the POP instruction. The POP instruction discards the current TOS by decrementing the Stack Pointer. The previous value pushed onto the stack then becomes the TOS value.

5.2.4 STACK FULL/UNDERFLOW RESETS

These Resets are enabled by programming the STVR bit in Configuration Register 4L. When the STVR bit is cleared, a full or underflow condition will set the appropriate STKFUL or STKUNF bit, but not cause a device Reset. When the STVR bit is set, a full or underflow condition will set the appropriate STKFUL or STKUNF bit and then cause a device Reset. The STKFUL or STKUNF bits are cleared by the user software or a Power-on Reset.

8.0 8 x 8 HARDWARE MULTIPLIER

8.1 Introduction

An 8 x 8 hardware multiplier is included in the ALU of the PIC18F1220/1320 devices. By making the multiply a hardware operation, it completes in a single instruction cycle. This is an unsigned multiply that gives a 16-bit result. The result is stored into the 16-bit product register pair (PRODH:PRODL). The multiplier does not affect any flags in the Status register.

Making the 8 x 8 multiplier execute in a single cycle gives the following advantages:

- Higher computational throughput
- Reduces code size requirements for multiply algorithms

The performance increase allows the device to be used in applications previously reserved for Digital Signal Processors.

Table 8-1 shows a performance comparison between Enhanced devices using the single-cycle hardware multiply and performing the same function without the hardware multiply.

TABLE 8-1: PERFORMANCE COMPARISON

Routine	Multiply Method	Program Memory (Words)	Cycles (Max)	Time		
				@ 40 MHz	@ 10 MHz	@ 4 MHz
8 x 8 unsigned	Without hardware multiply	13	69	6.9 μs	27.6 μs	69 μs
	Hardware multiply	1	1	100 ns	400 ns	1 μs
8 x 8 signed	Without hardware multiply	33	91	9.1 μs	36.4 μs	91 μs
	Hardware multiply	6	6	600 ns	2.4 μs	6 μs
16 x 16 unsigned	Without hardware multiply	21	242	24.2 μs	96.8 μs	242 μs
	Hardware multiply	28	28	2.8 μs	11.2 μs	28 μs
16 x 16 signed	Without hardware multiply	52	254	25.4 μs	102.6 μs	254 μs
	Hardware multiply	35	40	4 μs	16 μs	40 μs

8.2 Operation

Example 8-1 shows the sequence to do an 8 x 8 unsigned multiply. Only one instruction is required when one argument of the multiply is already loaded in the WREG register.

Example 8-2 shows the sequence to do an 8 x 8 signed multiply. To account for the sign bits of the arguments, each argument's Most Significant bit (MSb) is tested and the appropriate subtractions are done.

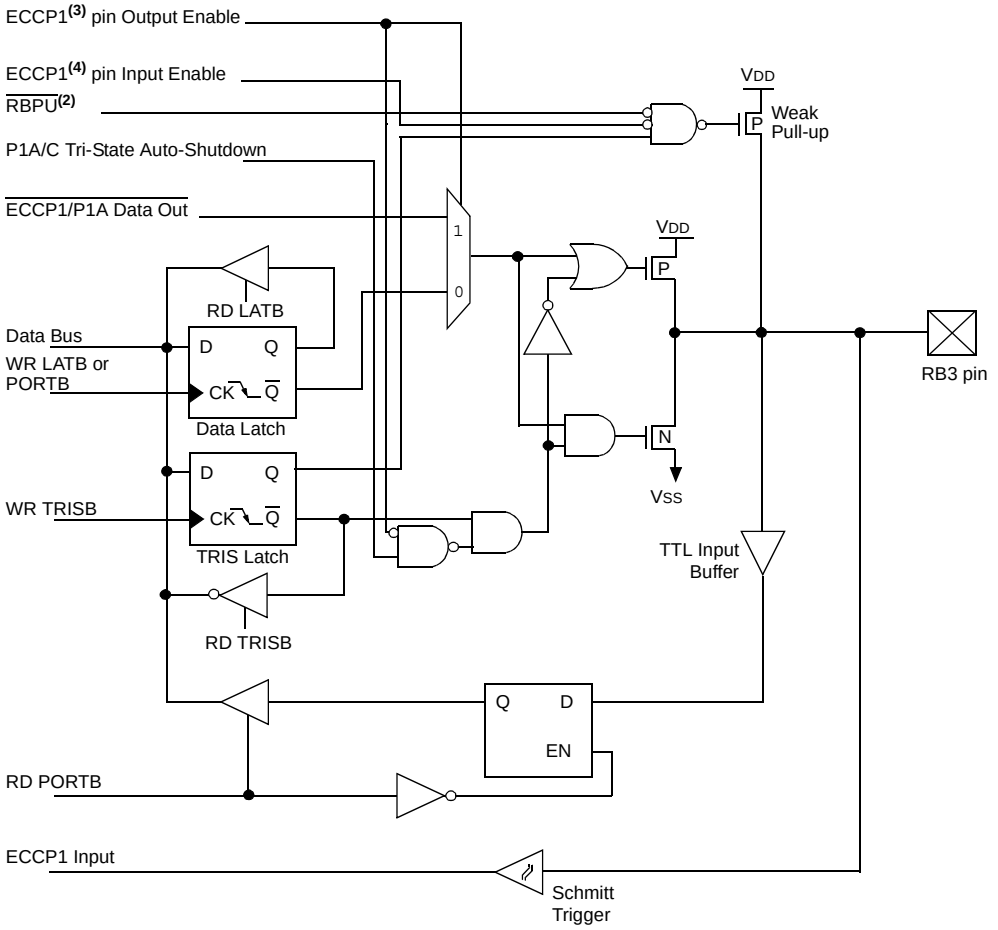
EXAMPLE 8-1: 8 x 8 UNSIGNED MULTIPLY ROUTINE

```
MOVF    ARG1, W     ;
MULWF   ARG2        ; ARG1 * ARG2 ->
                    ; PRODH:PRODL
```

EXAMPLE 8-2: 8 x 8 SIGNED MULTIPLY ROUTINE

```
MOVF    ARG1, W
MULWF   ARG2        ; ARG1 * ARG2 ->
                    ; PRODH:PRODL
BTFSC   ARG2, SB    ; Test Sign Bit
SUBWF   PRODH, F    ; PRODH = PRODH
                    ;         - ARG1
MOVF    ARG2, W
BTFSC   ARG1, SB    ; Test Sign Bit
SUBWF   PRODH, F    ; PRODH = PRODH
                    ;         - ARG2
```

FIGURE 10-10: BLOCK DIAGRAM OF RB3/CCP1/P1A PIN



Note 1: I/O pins have diode protection to VDD and VSS.

2: To enable weak pull-ups, set the appropriate TRIS bit(s) and clear the $\overline{\text{RBPU}}$ bit (INTCON2<7>).

3: ECCP1 pin output enable active for any PWM mode and Compare mode, where CCP1M<3:0> = 1000 or 1001.

4: ECCP1 pin input enable active for Capture mode only.

TABLE 10-3: PORTB FUNCTIONS

Name	Bit#	Buffer	Function
RB0/AN4/INT0	bit 0	TTL(1)/ST(2)	Input/output port pin, analog input or external interrupt input 0.
RB1/AN5/TX/CK/INT1	bit 1	TTL(1)/ST(2)	Input/output port pin, analog input, Enhanced USART Asynchronous Transmit, Addressable USART Synchronous Clock or external interrupt input 1.
RB2/P1B/INT2	bit 2	TTL(1)/ST(2)	Input/output port pin or external interrupt input 2. Internal software programmable weak pull-up.
RB3/CCP1/P1A	bit 3	TTL(1)/ST(3)	Input/output port pin or Capture1 input/Compare1 output/ PWM output. Internal software programmable weak pull-up.
RB4/AN6/RX/DT/KBI0	bit 4	TTL(1)/ST(4)	Input/output port pin (with interrupt-on-change), analog input, Enhanced USART Asynchronous Receive or Addressable USART Synchronous Data.
RB5/PGM/KBI1	bit 5	TTL(1)/ST(5)	Input/output port pin (with interrupt-on-change). Internal software programmable weak pull-up. Low-Voltage ICSP™ enable pin.
RB6/PGC/T1OSO/T13CKI/ P1C/KBI2	bit 6	TTL(1)/ST(5,6)	Input/output port pin (with interrupt-on-change), Timer1/ Timer3 clock input or Timer1oscillator output. Internal software programmable weak pull-up. Serial programming clock.
RB7/PGD/T1OSI/P1D/KBI3	bit 7	TTL(1)/ST(5)	Input/output port pin (with interrupt-on-change) or Timer1 oscillator input. Internal software programmable weak pull-up. Serial programming data.

Legend: TTL = TTL input, ST = Schmitt Trigger input

Note 1: This buffer is a TTL input when configured as a port input pin.

2: This buffer is a Schmitt Trigger input when configured as the external interrupt.

3: This buffer is a Schmitt Trigger input when configured as the CCP1 input.

4: This buffer is a Schmitt Trigger input when used as EUSART receive input.

5: This buffer is a Schmitt Trigger input when used in Serial Programming mode.

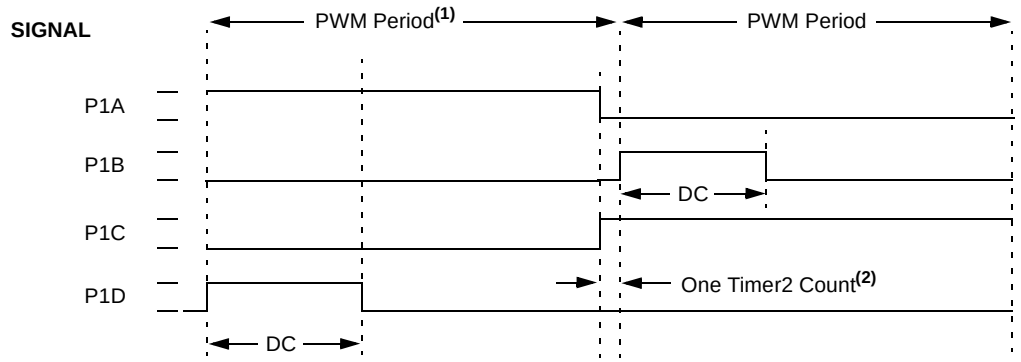
6: This buffer is a TTL input when used as the T13CKI input.

TABLE 10-4: SUMMARY OF REGISTERS ASSOCIATED WITH PORTB

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxq qqqq	uuuu uuuu
LATB	LATB Data Output Register								xxxx xxxx	uuuu uuuu
TRISB	PORTB Data Direction Register								1111 1111	1111 1111
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
INTCON2	$\overline{\text{RBPU}}$	INTEDG0	INTEDG1	INTEDG2	—	TMR0IP	—	RBIP	1111 -1-1	1111 -1-1
INTCON3	INT2IP	INT1IP	—	INT2IE	INT1IE	—	INT2IF	INT1IF	11-0 0-00	11-0 0-00
ADCON1	—	PCFG6	PCFG5	PCFG4	PCFG3	PCFG2	PCFG1	PCFG0	-000 0000	-000 0000

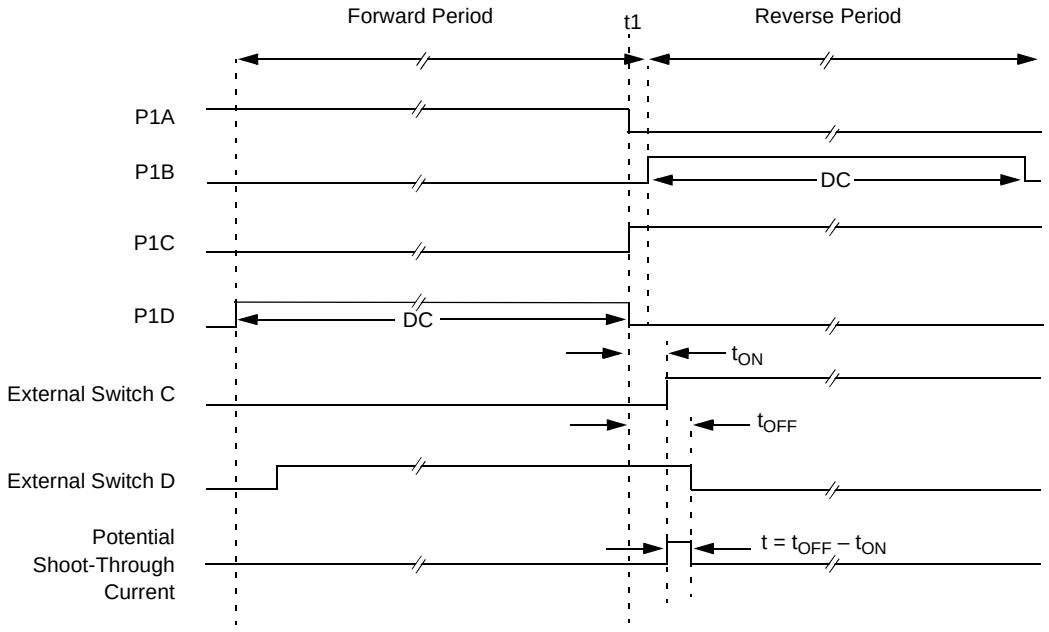
Legend: x = unknown, u = unchanged, q = value depends on condition. Shaded cells are not used by PORTB.

FIGURE 15-10: PWM DIRECTION CHANGE (ACTIVE-HIGH)



Note 1: The direction bit in the CCP1 Control register (CCP1CON<7>) is written any time during the PWM cycle.
2: When changing directions, the P1A and P1C toggle one Timer2 count before the end of the current PWM cycle. The modulated P1B and P1D signals are inactive at this time.

FIGURE 15-11: PWM DIRECTION CHANGE AT NEAR 100% DUTY CYCLE (ACTIVE-HIGH)



Note 1: t_{ON} is the turn-on delay of power switch QC and its driver.
2: t_{OFF} is the turn-off delay of power switch QD and its driver.

16.3.5 BREAK CHARACTER SEQUENCE

The Enhanced USART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. The Break character transmit consists of a Start bit, followed by twelve '0' bits and a Stop bit. The Frame Break character is sent whenever the SENDB and TXEN bits (TXSTA<3> and TXSTA<5>) are set while the Transmit Shift register is loaded with data. Note that the value of data written to TXREG will be ignored and all '0's will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

Note that the data value written to the TXREG for the Break character is ignored. The write simply serves the purpose of initiating the proper sequence.

The TRMT bit indicates when the transmit operation is active or Idle, just as it does during normal transmission. See Figure 16-9 for the timing of the Break character sequence.

16.3.5.1 Transmitting A Break Signal

The Enhanced USART module has the capability of sending the Break signal that is required by the LIN bus standard. The Break signal consists of a Start bit, followed by twelve '0' bits and a Stop bit. The Break signal is sent whenever the SENDB (TXSTA<3>) and TXEN (TXSTA<5>) bits are set and TXREG is loaded with data. The data written to TXREG will be ignored and all '0's will be transmitted.

SENDB is automatically cleared by hardware when the Break signal has been sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit indicates when the transmit operation is active or Idle, just as it does during normal transmission.

To send a Break Signal:

1. Configure the EUSART for asynchronous transmissions (steps 1-5). Initialize the SPBRG register for the appropriate baud rate. If a high-speed baud rate is desired, set bit BRGH (see **Section 16.2 "EUSART Baud Rate Generator (BRG)"**).
2. Enable the asynchronous serial port by clearing bit SYNC and setting bit SPEN.
3. If interrupts are desired, set enable bit TXIE.
4. If 9-bit transmission is desired, set transmit bit TX9. Can be used as address/data bit.
5. Enable the transmission by setting bit TXEN, which will also set bit TXIF.
6. Set the SENDB bit.
7. Load a byte into TXREG. This triggers sending a Break signal. The Break signal is complete when TRMT is set. SENDB will also be cleared.

See Figure 16-9 for the timing of the Break signal sequence.

16.3.6 RECEIVING A BREAK CHARACTER

The Enhanced USART module can receive a Break character in two ways.

The first method forces configuration of the baud rate at a frequency of 9/13 the typical speed. This allows for the Stop bit transition to be at the correct sampling location (12 bits for Break versus Start bit and eight data bits for typical data).

The second method uses the auto-wake-up feature described in **Section 16.3.4 "Auto-Wake-up on Sync Break Character"**. By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Rate Detect feature. For both methods, the user can set the ABD bit before placing the EUSART in its Sleep mode.

16.3.6.1 Transmitting a Break Sync

The following sequence will send a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to set up the Break character.
3. Load the TXREG with a dummy character to initiate transmission (the value is ignored).
4. Write '55h' to TXREG to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware. The Sync character now transmits in the preconfigured mode. When the TXREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXREG.

TABLE 16-8: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	—	ADIF	RCIF	TXIF	—	CCP1IF	TMR2IF	TMR1IF	-000 -000	-000 -000
PIE1	—	ADIE	RCIE	TXIE	—	CCP1IE	TMR2IE	TMR1IE	-000 -000	-000 -000
IPR1	—	ADIP	RCIP	TXIP	—	CCP1IP	TMR2IP	TMR1IP	-111 -111	-111 -111
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	0000 000x
RCREG	EUSART Receive Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	0000 0010	0000 0010
BAUDCTL	—	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	-1-1 0-00	-1-1 0-00
SPBRGH	Baud Rate Generator Register High Byte								0000 0000	0000 0000
SPBRG	Baud Rate Generator Register Low Byte								0000 0000	0000 0000

Legend: x = unknown, – = unimplemented, read as '0'. Shaded cells are not used for synchronous master reception.

17.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) converter module has seven inputs for the PIC18F1220/1320 devices. This module allows conversion of an analog input signal to a corresponding 10-bit digital number.

A new feature for the A/D converter is the addition of programmable acquisition time. This feature allows the user to select a new channel for conversion and to set the GO/$\overline{\text{DONE}}$ bit immediately. When the GO/$\overline{\text{DONE}}$ bit is set, the selected channel is sampled for the programmed acquisition time before a conversion is actually started. This removes the firmware overhead that may have been required to allow for an acquisition (sampling) period (see Register 17-3 and **Section 17.3 "Selecting and Configuring Automatic Acquisition Time"**).

The module has five registers:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)
- A/D Control Register 2 (ADCON2)

The ADCON0 register, shown in Register 17-1, controls the operation of the A/D module. The ADCON1 register, shown in Register 17-2, configures the functions of the port pins. The ADCON2 register, shown in Register 17-3, configures the A/D clock source, programmed acquisition time and justification.

18.1 Control Register

The Low-Voltage Detect Control register controls the operation of the Low-Voltage Detect circuitry.

REGISTER 18-1: LVDCON: LOW-VOLTAGE DETECT CONTROL REGISTER

U-0	U-0	R-0/0	R/W-0/0	R/W-0/0	R/W-1/1	R/W-0/0	R/W-1/1
—	—	IRVST	LVDEN	LVDL3	LVDL2	LVDL1	LVDL0
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the Low-Voltage Detect logic will generate the interrupt flag at the specified voltage range
0 = Indicates that the Low-Voltage Detect logic will not generate the interrupt flag at the specified voltage range and the LVD interrupt should not be enabled

bit 4 **LVDEN:** Low-Voltage Detect Power Enable bit
1 = Enables LVD, powers up LVD circuit
0 = Disables LVD, powers down LVD circuit

bit 3-0 **LVDL<3:0>:** Low-Voltage Detection Limit bits(1)
1111 = External analog input is used (input comes from the LVDIN pin)
1110 = 4.04V-5.15V
1101 = 3.76V-4.79V
1100 = 3.58V-4.56V
1011 = 3.41V-4.34V
1010 = 3.23V-4.11V
1001 = 3.14V-4.00V
1000 = 2.96V-3.77V
0111 = 2.70V-3.43V
0110 = 2.53V-3.21V
0101 = 2.43V-3.10V
0100 = 2.25V-2.86V
0011 = 2.16V-2.75V
0010 = 1.99V-2.53V
0001 = Reserved
0000 = Reserved

Note 1: LVDL<3:0> modes, which result in a trip point below the valid operating voltage of the device, are not tested.

REGISTER 19-2: CONFIG2L: CONFIGURATION REGISTER 2 LOW (BYTE ADDRESS 300002h)

U-0	U-0	U-0	U-0	R/P-1	R/P-1	R/P-1	R/P-1
—	—	—	—	BORV1	BORV0	BOR(1)	$\overline{\text{PWRTEN}}$(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	P = Programmable bit

bit 7-4 **Unimplemented:** Read as ‘0’

bit 3-2 **BORV<1:0>:** Brown-out Reset Voltage bits
- 11 = Reserved
- 10 = V_{BOR} set to 2.7V
- 01 = V_{BOR} set to 4.2V
- 00 = V_{BOR} set to 4.5V

bit 1 **BOR:** Brown-out Reset Enable bit(1)
- 1 = Brown-out Reset enabled
- 0 = Brown-out Reset disabled

bit 0 **$\overline{\text{PWRTEN}}$:** Power-up Timer Enable bit(1)
- 1 = PWRT disabled
- 0 = PWRT enabled

Note 1: The Power-up Timer is decoupled from Brown-out Reset, allowing these features to be independently controlled.

19.2 Watchdog Timer (WDT)

For PIC18F1220/1320 devices, the WDT is driven by the INTRC source. When the WDT is enabled, the clock source is also enabled. The nominal WDT period is 4 ms and has the same stability as the INTRC oscillator.

The 4 ms period of the WDT is multiplied by a 16-bit postscaler. Any output of the WDT postscaler is selected by a multiplexer, controlled by bits in Configuration Register 2H. Available periods range from 4 ms to 131.072 seconds (2.18 minutes). The WDT and postscaler are cleared when any of the following events occur: execute a SLEEP or CLRWDT instruction, the IRCF bits (OSCCON<6:4>) are changed or a clock failure has occurred.

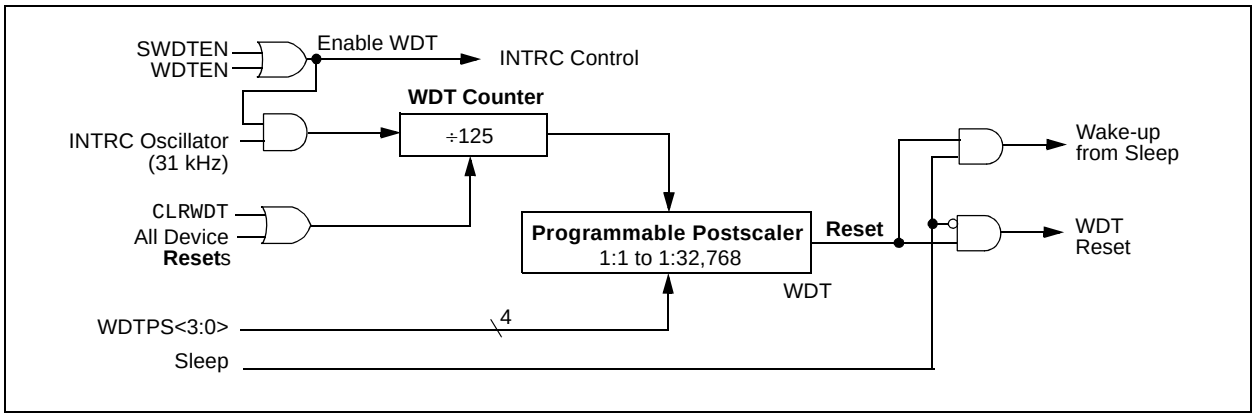
Adjustments to the internal oscillator clock period using the OSCTUNE register also affect the period of the WDT by the same factor. For example, if the INTRC period is increased by 3%, then the WDT period is increased by 3%.

Note 1:	The CLRWDT and SLEEP instructions clear the WDT and postscaler counts when executed.
2:	Changing the setting of the IRCF bits (OSCCON<6:4>) clears the WDT and postscaler counts.
3:	When a CLRWDT instruction is executed the postscaler count will be cleared.

19.2.1 CONTROL REGISTER

Register 19-14 shows the WDTCON register. This is a readable and writable register, which contains a control bit that allows software to override the WDT enable Configuration bit, only if the Configuration bit has disabled the WDT.

FIGURE 19-1: WDT BLOCK DIAGRAM



REGISTER 19-14: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0/0
—	—	—	—	—	—	—	SWDTEN(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-m/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-1 **Unimplemented:** Read as ‘0’

bit 0 **SWDTEN:** Software Controlled Watchdog Timer Enable bit(1)

1 = Watchdog Timer is on
0 = Watchdog Timer is off

Note 1: This bit has no effect if the Configuration bit, WDTEN (CONFIG2H<0>), is enabled.

BCF **Bit Clear f**

Syntax: [*label*] BCF f,b[,a]

Operands: $0 \le f \le 255$
$0 \le b \le 7$
$a \in [0,1]$

Operation: $0 \rightarrow f<b>$

Status Affected: None

Encoding:

1001	bbba	ffff	ffff

Description: Bit 'b' in register 'f' is cleared. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: `BCF FLAG_REG, 7`

Before Instruction
FLAG_REG = 0xC7
After Instruction
FLAG_REG = 0x47

BN **Branch if Negative**

Syntax: [*label*] BN n

Operands: $-128 \le n \le 127$

Operation: if Negative bit is '1'
$(PC) + 2 + 2n \rightarrow PC$

Status Affected: None

Encoding:

1110	0110	nnnn	nnnn

Description: If the Negative bit is '1', then the program will branch.
The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a 2-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: `HERE BN Jump`

Before Instruction
PC = address (HERE)
After Instruction
If Negative = 1;
PC = address (Jump)
If Negative = 0;
PC = address (HERE + 2)

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 1048575$

Operation: $k \rightarrow PC<20:1>$

Status Affected: None

Encoding:

1st word (k<7:0>)	1110	1111	k_7kkk	$kkkk_0$
2nd word(k<19:8>)	1111	$k_{19}kkk$	kkkk	$kkkk_8$

Description: GOTO allows an unconditional branch anywhere within the entire 2-Mbyte memory range. The 20-bit value 'k' is loaded into PC<20:1>. GOTO is always a 2-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	No operation	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: GOTO THERE

After Instruction
PC = Address (THERE)

INCF **Increment f**

Syntax: [*label*] INCF f [,d [,a]]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (f) + 1 → dest

Status Affected: C, DC, N, OV, Z

Encoding:

0010	10da	ffff	ffff

Description: The contents of register 'f' are incremented. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed back in register 'f' (default). If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: INCF CNT

Before Instruction
CNT = 0xFF
Z = 0
C = ?
DC = ?

After Instruction
CNT = 0x00
Z = 1
C = 1
DC = 1

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f [,d [,a]]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) .XOR. (f) → dest

Status Affected: N, Z

Encoding:

0001	10da	ffff	ffff

Description: Exclusive OR the contents of W with register 'f'. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in the register 'f' (default). If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' is '1', then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: XORWF REG

Before Instruction
REG = 0xAF
W = 0xB5

After Instruction
REG = 0x1A
W = 0xB5

22.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings(†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$ and RA4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +5.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Voltage on RA4 with respect to Vss ..... 0V to +8.5V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$Pdis = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}/V_{PP}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{MCLR}/V_{PP}$ pin, rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

23.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean – 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

FIGURE 23-1: TYPICAL IDD vs. FOSC OVER VDD PRI_RUN, EC MODE, +25°C

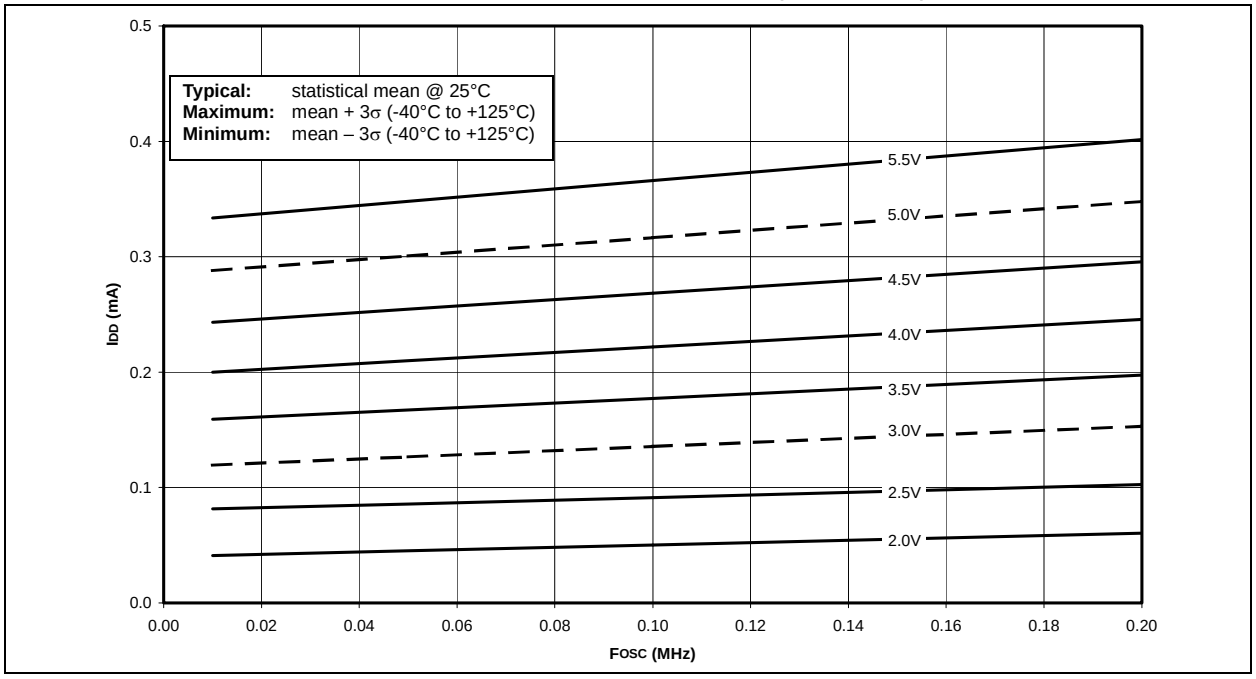


FIGURE 23-2: MAXIMUM IDD vs. FOSC OVER VDD PRI_RUN, EC MODE, -40°C TO +85°C

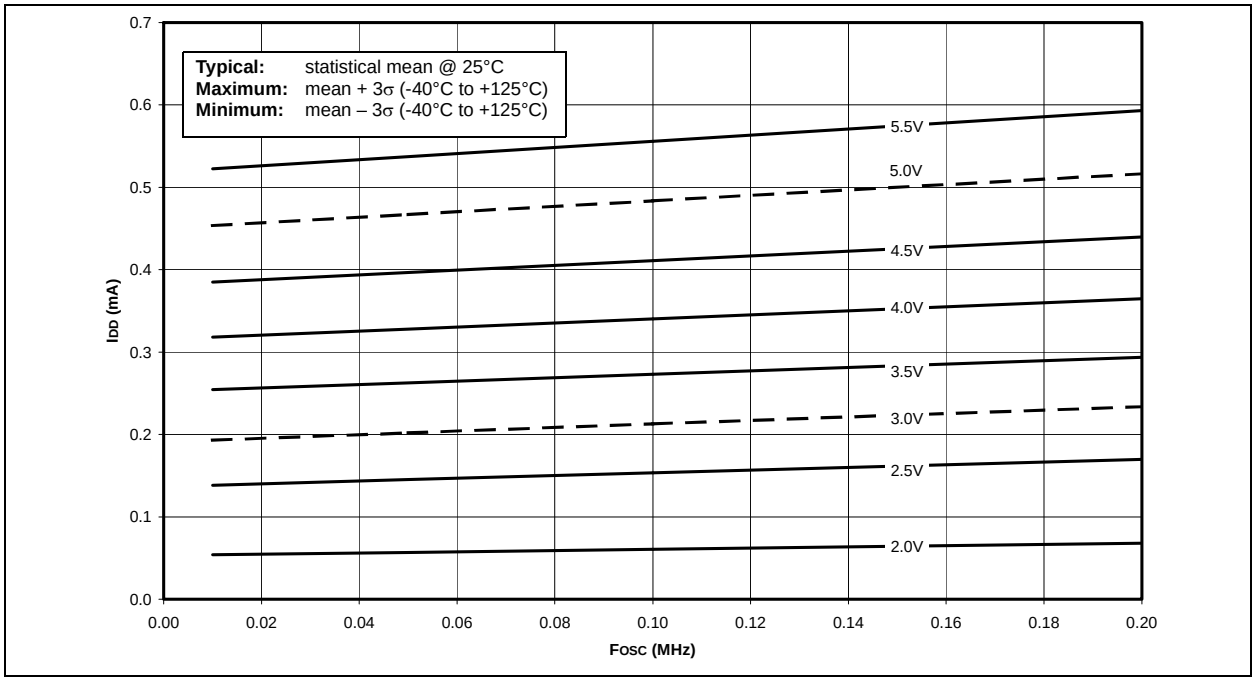


FIGURE 23-13: TYPICAL IDD vs. FOSC OVER VDD PRI_IDLE, EC MODE, +25°C

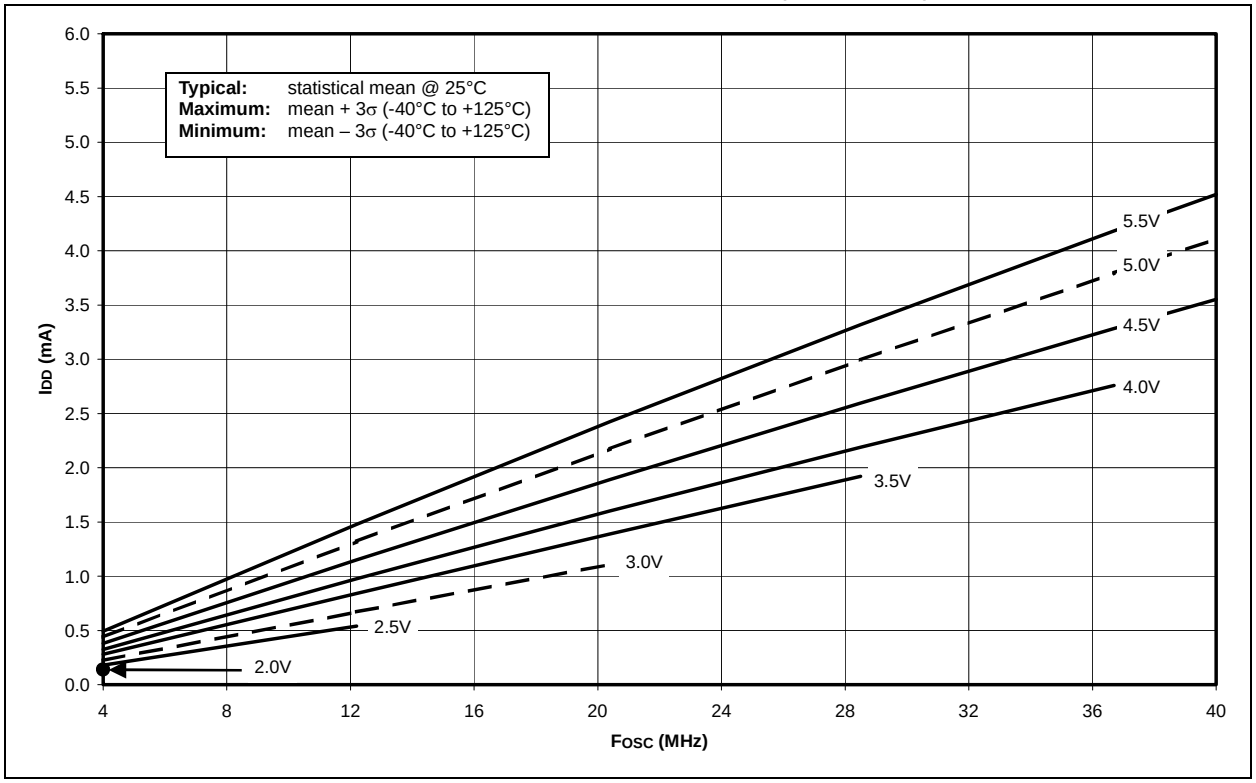
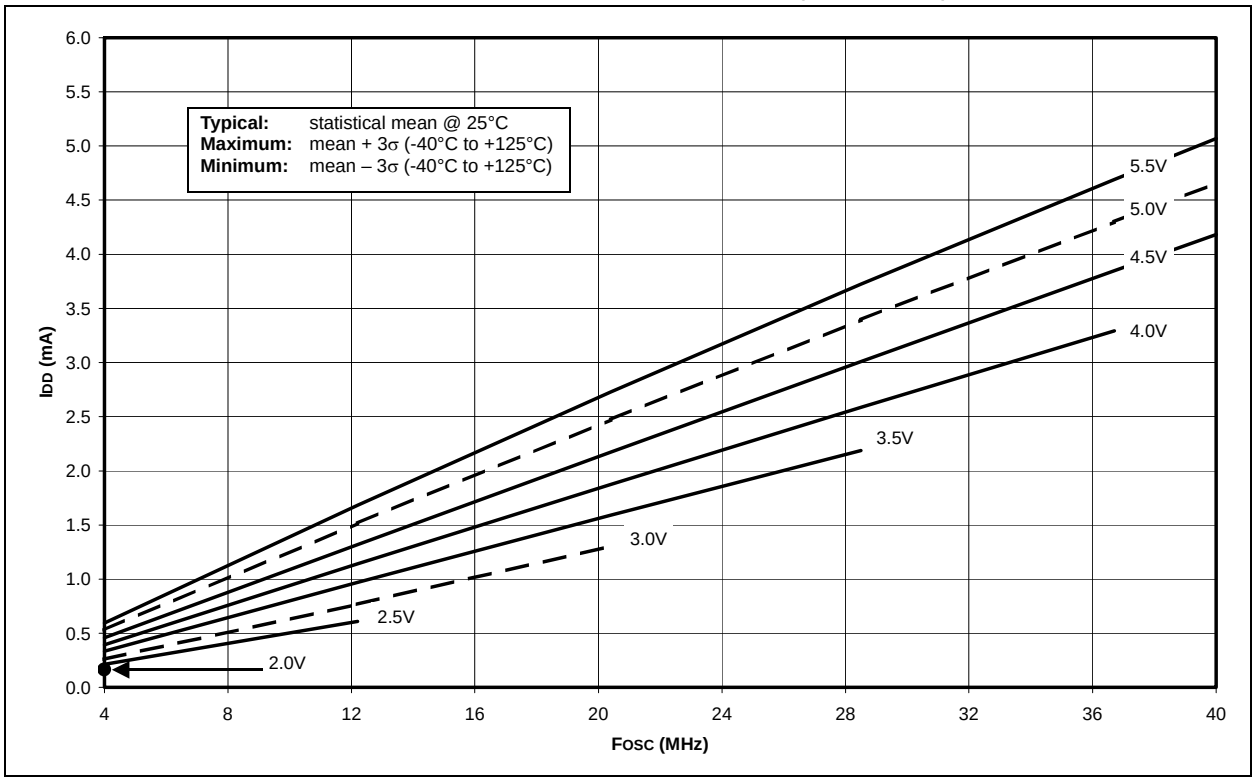


FIGURE 23-14: MAXIMUM IDD vs. FOSC OVER VDD PRI_IDLE, EC MODE, -40°C TO +125°C

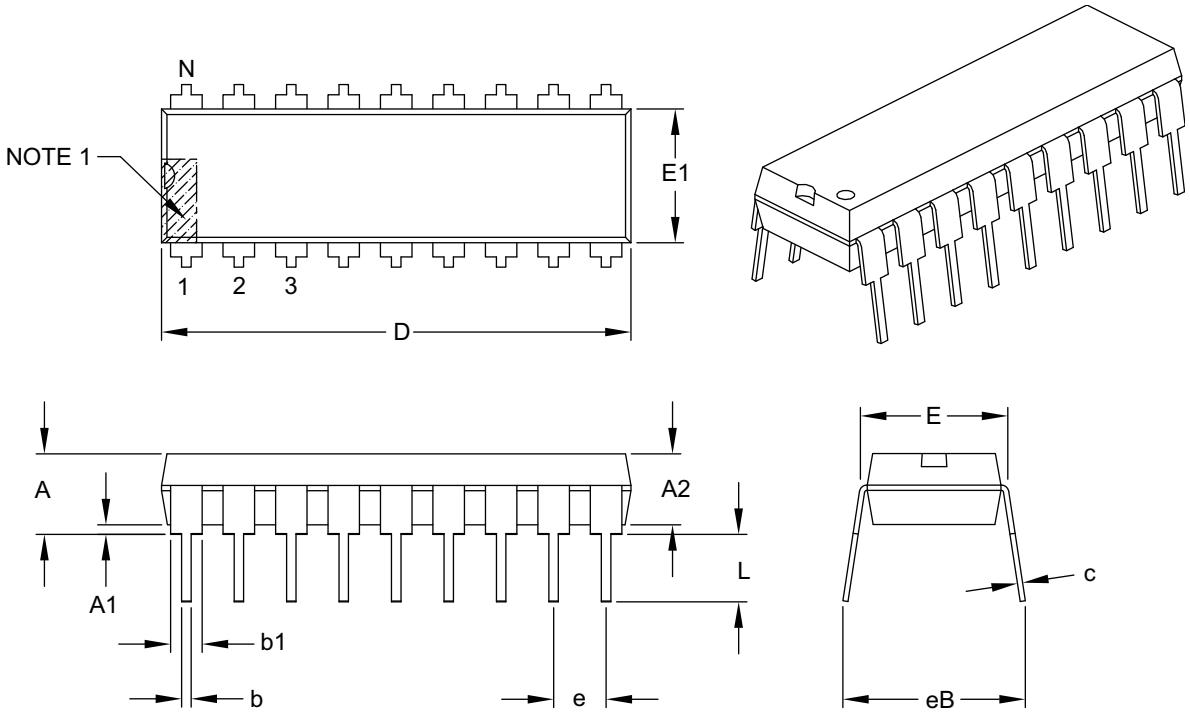


24.2 Package Details

The following sections give the technical details of the packages.

18-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		18	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.880	.900	.920
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.014
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

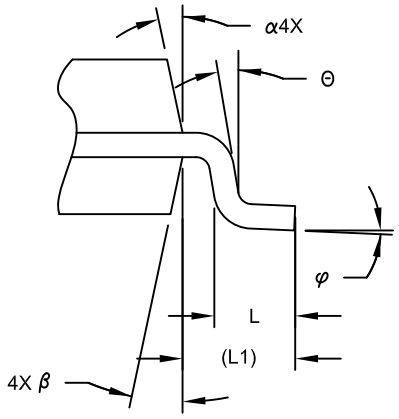
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

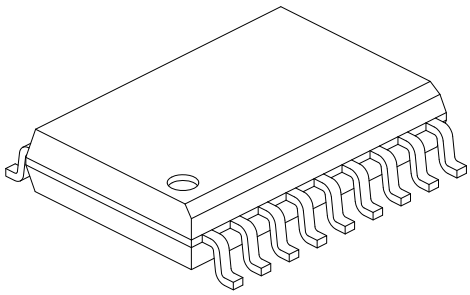
Microchip Technology Drawing C04-007B

18-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		18	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		11.55 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-051C Sheet 2 of 2